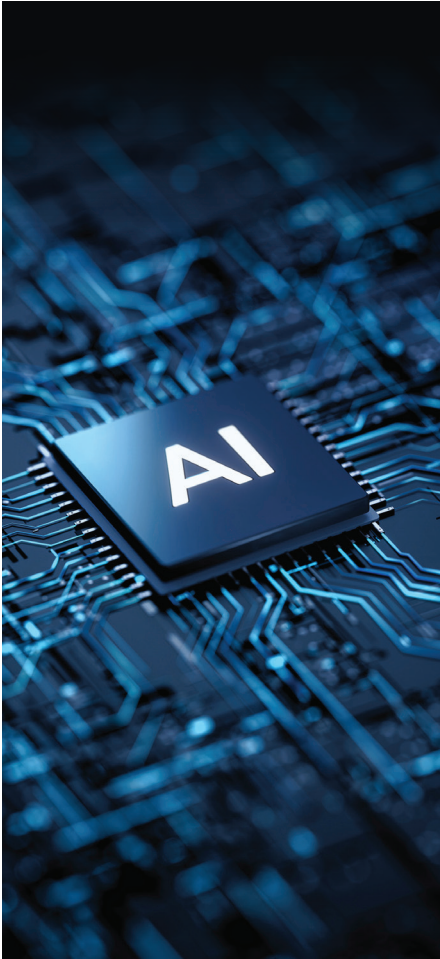




Advanced Data Center Solutions Neocloud & AI Factories Environments

EMPOWERING FUTURE MIGRATION PATHS



AI infrastructure environments demand ultra-high-speed, high-density connectivity capable of supporting rapidly evolving GPU architectures required for AI training, Inference, power density & unprecedented bandwidth. As AI clusters continue to scale, high-speed interconnects and high-density fiber systems become increasingly important for supporting low-latency performance, deployment speed and scalable AI growth across GPU, compute, network and storage environments.

Siemon supports Neocloud providers and AI factory environments with cutting edge high-density fiber infrastructure and high-speed interconnect solutions across Ethernet and InfiniBand™ architectures. Designed for scalable AI deployments, Siemon's innovative connectivity solutions help simplify infrastructure expansion and support evolving AI fabrics and future migration strategies.

Supporting Ethernet and InfiniBand networks, Siemon helps customers deploy scalable, interoperable AI infrastructure aligned to evolving performance requirements across multi-vendor environments, including NVIDIA GPU platforms.

Supporting **Rapid AI** Infrastructure Growth

End-to-End AI Connectivity

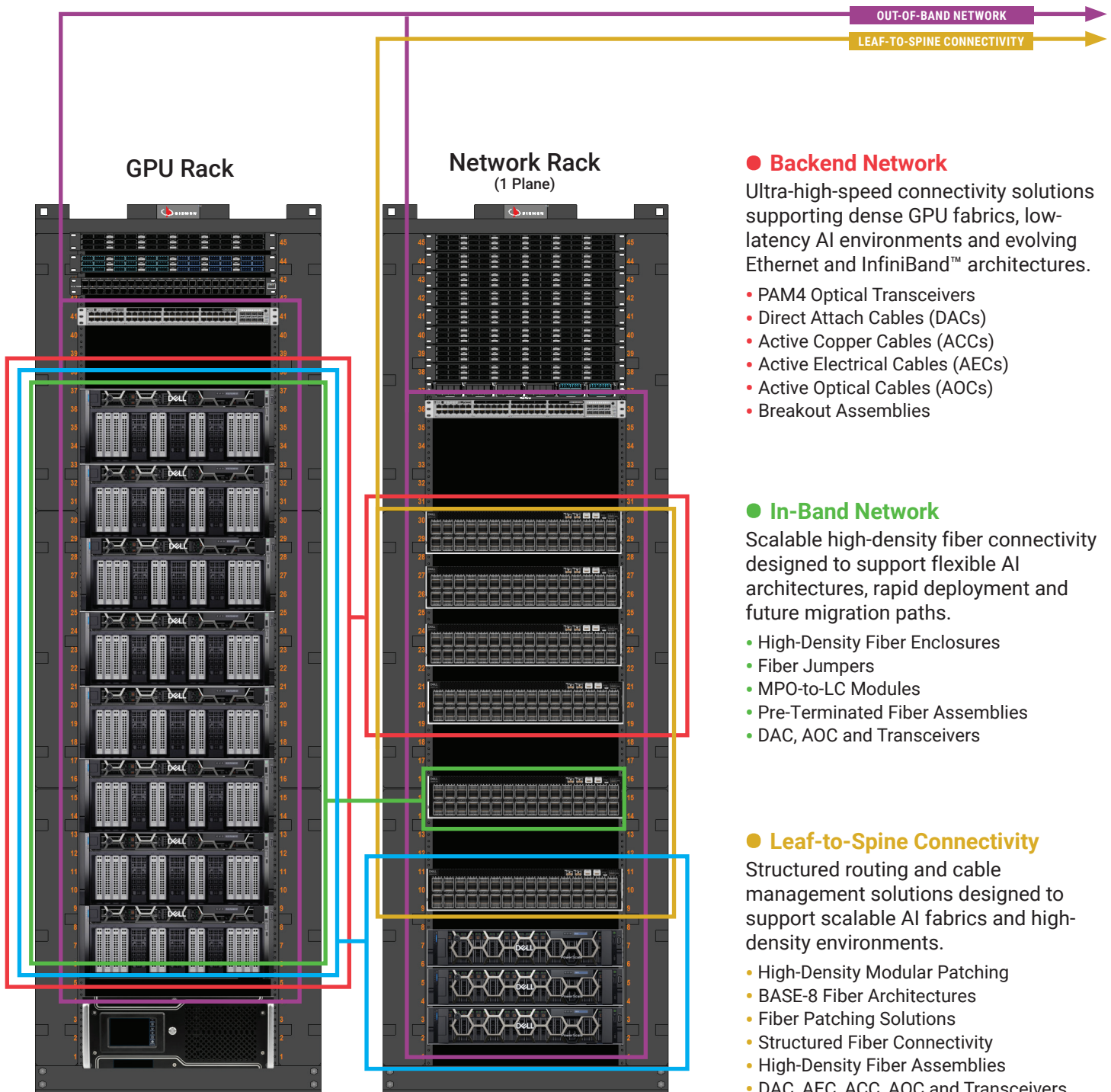
High-speed connectivity solutions, including transceivers, support today's highest-speed, high-density AI deployments, while structured fiber cabling provides a scalable foundation for emerging terabit network architectures.

Proven Multi-Vendor Compatibility

Interoperable connectivity designed to integrate seamlessly with leading AI networking platforms, including NVIDIA, Dell and Arista.

Global Delivery & Deployment

Worldwide logistics, pre-terminated solutions and technical expertise helping accelerate AI infrastructure rollouts across global locations.



Scale: Middle-of-Row

● Backend Network

Ultra-high-speed connectivity solutions supporting dense GPU fabrics, low-latency AI environments and evolving Ethernet and InfiniBand™ architectures.

- PAM4 Optical Transceivers
- Direct Attach Cables (DACs)
- Active Copper Cables (ACCs)
- Active Electrical Cables (AECs)
- Active Optical Cables (AOCs)
- Breakout Assemblies

● In-Band Network

Scalable high-density fiber connectivity designed to support flexible AI architectures, rapid deployment and future migration paths.

- High-Density Fiber Enclosures
- Fiber Jumpers
- MPO-to-LC Modules
- Pre-Terminated Fiber Assemblies
- DAC, AOC and Transceivers

● Leaf-to-Spine Connectivity

Structured routing and cable management solutions designed to support scalable AI fabrics and high-density environments.

- High-Density Modular Patching
- BASE-8 Fiber Architectures
- Fiber Patching Solutions
- Structured Fiber Connectivity
- High-Density Fiber Assemblies
- DAC, AEC, ACC, AOC and Transceivers

● Out-of-Band Network

Dedicated copper connectivity supporting management, monitoring and control networks.

- UTP or Shielded Category 6/6A
- Copper Patch Panels

● Storage Network

Reliable, scalable fiber connectivity supporting high-performance storage environments and growing AI data demands.

- Fiber Enclosures
- Fiber Adapter Plates
- Fiber Splice Enclosures
- MPO-to-LC Modules
- Splice Cassettes
- DAC, AOC and Transceivers